

TOSHIBA CORPORATION

Semiconductor Company

Document Change Notification

The purpose of this notification is to inform customers about the launch of the Pb-free version of the device. The introduction of a Pb-free replacement affects the datasheet. Please understand that this notification is intended as a temporary substitute for a revision of the datasheet.

Changes to the datasheet may include the following, though not all of them may apply to this particular device.

- 1. Part number
 - Example: TMPxxxxxF TMPxxxxxFG

All references to the previous part number were left unchanged in body text. The new part number is indicated on the prelims pages (cover page and this notification).

2. Package code and package dimensions (

Example: LQFP100-P-1414-0.50C \ LQFP100-P-1414-0.50F

All references to the previous package code and package dimensions were left unchanged in body text. The new ones are indicated on the prelims pages.

3. Addition of notes on lead solderability

Now that the device is Pb-free, notes on lead solderability have been added.

4. RESTRICTIONS ON PRODUCT USE

The previous (obsolete) provision might be left unchanged on page 1 of body text. A new replacement is included on the next page.

5. Publication date of the datasheet

The publication date at the lower right corner of the prelims pages applies to the new device.

1. Part number

2. Package code and dimensions

Previous Part Number (in Body Text)	Previous Package Code (in Body Text)	New Part Number	New Package Code	OTP
TMP87PS71AF	QFP80-P-1420-0.80B	TMP87PS71AFG	QFP80-P-1420-0.80B	—

*: For the dimensions of the new package, see the attached Package Dimensions diagram.

3. Addition of notes on lead solderability

The following solderability test is conducted on the new device.

Lead solderability of Pb-free devices (with the G suffix)

Test	Test Conditions	Remark
Solderability	 (1) Use of Lead (Pb) solder bath temperature = 230°C dipping time = 5 seconds the number of times = once use of R-type flux (2) Use of Lead (Pb)-Free solder bath temperature = 245°C dipping time = 5 seconds the number of times = once use of R-type flux 	Leads with over 95% solder coverage till lead forming are acceptable.

4. RESTRICTIONS ON PRODUCT USE

The following replaces the "RESTRICTIONS ON PRODUCT USE" on page 1 of body text.

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- For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance/Handling Precautions.

5. Publication date of the datasheet

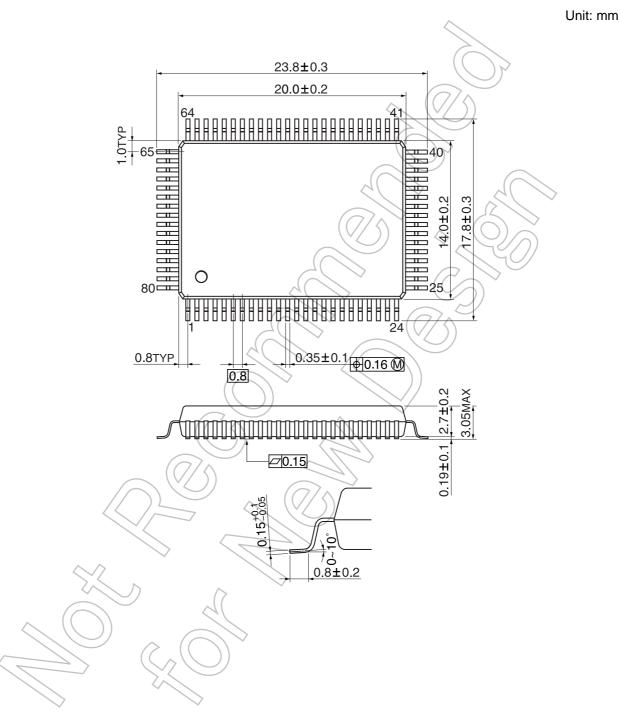
The publication date of this datasheet is printed at the lower right corner of this notification.

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(Annex)

Package Dimensions

QFP80-P-1420-0.80B



CMOS 8-Bit Microcontroller

TMP87PS71AF

The TMP87PS71A is a One-Time PROM microcontroller with low-power 480 K bits (60 Kbytes) electrically programmable read only memory for the TMP87CS71B system evaluation. The TMP87PS71A is pin compatible with the TMP87CS71B. The operations possible with the TMP87CS71B can be performed by writing programs to PROM. The TMP87PS71A can write and verify in the same way as the TC571000D using an adaptor socket BM11107 and an EPROM programmer.

Product No.	OTP	RAM	Package	Adapter Socket
TMP87PS71AF	60 K x 8 bits	2.0 K x 8 bits	P-QFP80-1420-0.80B	BM11107
			P-QFP80-14	
	(TMP87PS71AF

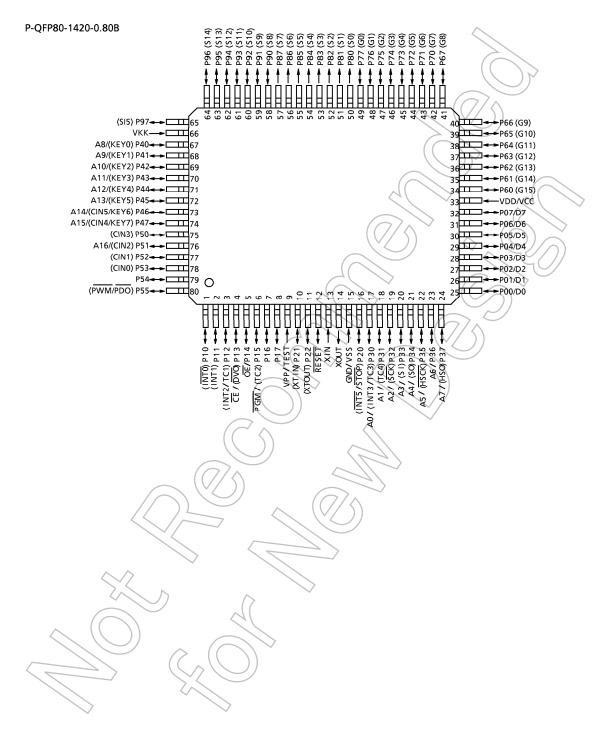
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- For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance / Handling Precautions.
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- making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.
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Pin Assignments (Top View)



Pin Functions

The TMP87PS71A has two modes: MCU and PROM.

(1) MCU mode

In this mode, the TMP87PS71A is pin compatible with the TMP87CS71B (fix the TEST pin at low level).

(2) PROM mode

Pin Name (PROM mode)	Input/Output	Functions	Pin Name (MCU mode)
A16 A15 to A8 A7 to A0	Input	PROM address inputs	P51 P47 to P40 P37 to P30
D7 to D0	I/O	PROM data input/outputs	P07 to P00
CE		Chip enable signal input (active low)	P13
OE	Input	Output enable signal input (active low)	P14
PGM		Program control input (active low)	P15
VPP		+ 12.75 V/5 V (Program supply voltage)	TEST
vcc	Power supply	+ 6.25 V/5 V	VDD
GND		ov	VSS
P55 to P52		Pull-down with resistance for input processing	
P11			
P21		PROM mode setting pin. Be fixed at high level.	
P50 P17, P16 P12, P10	HO	PROM mode setting pin. Be fixed at low level.	
P22, P20 RESET			
XIN XOUT	Jhput Output	Connect an 8 MHz oscillator to stabilize the internal state.	
VKK	VFT power supply	GND	
P97 to P90	1/0		
P87 to P80	Output		
P77 to P70	1/2	Dopen	
P67 to P60	I/O		

Operational Description

The following explains the TMP87PS71A hardware configuration and operation. The configuration and functions of the TMP87PS71A are the same as those of the TMP87CS71B, except in that a one-time PROM is used instead of an on-chip mask ROM.

The TMP87PS71A is placed in the *single-clock* mode during reset. To use the dual-clock mode, the low-frequency oscillator should be turned on by executing [SET (SYSCR2). XTEN] instruction at the beginning of the program.

1. Operating Mode

The TMP87PS71A has two modes: MCU and PROM.

1.1 MCU Mode

The MCU mode is activated by fixing the TEST/VPP pin at low level.

In the MCU mode, operation is the same as with the TMP87CS71B (the TEST/VPP pin cannot be used open because it has no built-in pull-down resistance).

1.1.1 Program Memory

The TMP87PS71A has a 60 K \times 8 bits (addresses 1100_H to FFFF_H in the MCU mode, addresses 11100_H to 1FFFF_H in the PROM mode) of program memory (OTP).

To use the TMP87PS71A as the system evaluation for the TMP87CS71B, the program should be written to the program memory area as shown in Figure 1-1.

Note: When accessing addresses $00000_{\rm H}$ to $110FF_{\rm H}$ of program memory in the PROM mode, blank, read or verify mode may not be guaranteed the operation; use addresses $11100_{\rm H}$ to $1FFFF_{\rm H}$.

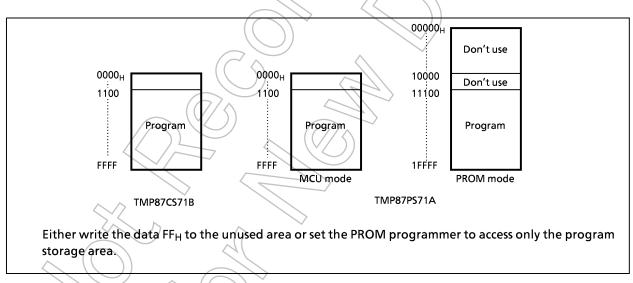


Figure 1-1. Program Memory Area

1.1.2 Data Memory

The TMP87PS71A has an on-chip 2.0 K \times 8 bits data memory (static RAM).

1.1.3 Input/Output Circuitry

(1) Control pins

The control pins of the TMP87PS71A is the same as those of the TMP87CS71B except that the TEST pin has is no built-in pull-down resistance.

Note: The pull-down resistance is not included. $R = 1 k\Omega (typ.)$
Figure 1-2. TEST Pin
(2) I/O ports The I/O circuitries of TMP87PS71A I/O ports are the same as the those of TMP87CS71B.
(C)

1.2 PROM Mode

The PROM mode is activated by setting the pins TEST, RESET and the ports P17 to P10, P22 to P20 and P50 as shown in Figure 1-3. The PROM mode is used to write and verify programs with a general-purpose PROM programmer. The high-speed programming mode can be used for program operation.

The TMP87PS71A is not supported an electric signature mode, so the ROM type must be set to TC571000D.

Set the adaptor socket switchs to "N" and "PS71".

Note: Please set the high-speed programming mode according to each manual of PROM programmer.

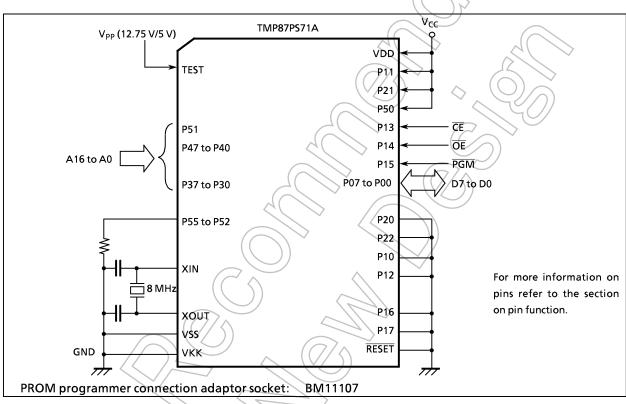


Figure 1-3. Setting for PROM Mode

1.2.1 Programming Flowchart (High-speed Programming Mode)

The high-speed programming mode is achieved by applying the program voltage (+ 12.75 V) to the VPP pin when Vcc = 6.25 V. After the address and input data are stable, the data is programmed by applying a single 0.1ms program pulse to the PGM input. The programmed data is verified. If incorrect, another 0.1 ms program pulse is applied. This process should be repeated (up to 25 times) until the program operates correctly. After that, change the address and input data, and program as before. When programming has been completed, the data in all addresses should be verified with Vcc = Vpp = 5 V.

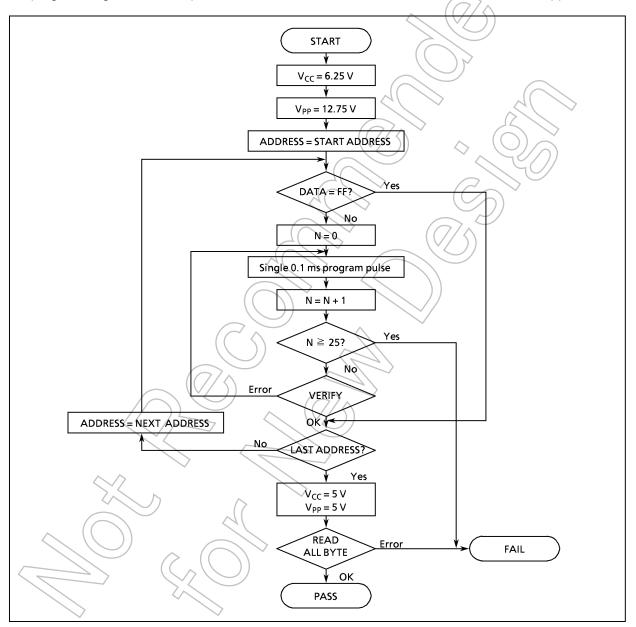


Figure 1-4. Flow Chart of High-Speed Programming

1.2.2 Writing Method for General-purpose PROM Program

- (1) Adapters BM11107: TMP87PS71AF
- (2) Adapter settingSwitch (SW1) is set to side N.Switch (SW2) is set to side PS71.
- (3) PROM programmer specifying
 - PROM type is specified to TC571000AD.
 Writing voltage: 12.75 V (high-speed program mode).
 - ii) Data transfer (copy) (note 1)
 In the TMP87PS71A, EPROM is within the addresses 11100_H to 1FFFF_H. Data is required to be transferred (copied) to the addresses where it is possible to write. The program area in MCU mode and PROM mode is referred to "Program memory area" in figure 1-1.

Ex. In the block transfer (copy) mode, executed as below. ROM capacity of 60KB: transferred addresses $01100_{\rm H}$ to 0FFFF_H to addresses 11100 to 1FFFF_H

- iii) Writing address is specified. (note 1). Start address: 11100_H End address: 1FFFF_H
- (4) Writing

Writing/Verifying is required to be executed in accordance with PROM programmer operating procedure.

- Note 1: The specifying method is referred to the PROM programmer description. Either write the data FF_H to the unused area or set the PROM programmer to access only the program storage area.
- Note 2: When MCU is set to an adapter or the adapter is set to PROM programmer, a position of pin 1 must be adjusted. If the setting is reversed, MCU, the adapter and PROM program is damaged.
- Note 3: The TMP87PS71A does not support the electric signature mode (hereinafter referred to as "signature"). If the signature is used in PROM program, a device is damaged due to applying $12V \pm 0.5V$ to the address pin 9 (A9). The signature must not be used.

Electrical Characteristics

Absolute Maximum Rati	ngs	$(V_{SS} = 0 V)$		
Parameter	Symbol	Conditions	Ratings	Unit
Supply Voltage	V _{DD}		– 0,3 to 6.5	V
Input Voltage	V _{IN}		-0.3 to V _{DD} + 0.3	V
Quitaut Valtage	V _{OUT1}	P2, P3, P4, P5, XOUT, RESET	- 0.3 to V _{DD} + 0.3	v
Output Voltage	V _{OUT2}	Source open drain ports	$V_{DD} - 40$ to $V_{DD} + 0.3$	v
	I _{OUT1}	P0, P1, P2, P3, P4, P5	3.2	
Output Current (Per 1 pin)	I _{OUT3}	T3 P8, P9 (segment outputs) - 12		mA
	I _{OUT4}	P6, P7 (digit outputs)	- 25	
Output Current (Tetel)	ΣI_{OUT1}	P0, P1, P2, P3, P4, P5	120	
Output Current (Total)	ΣI_{OUT2}	P6, P7, P8, P9	- 120	mA
Power Dissipation [Topr = 70°C]	PD		350	mW
Soldering Temperature (time)	Tsld		260 (10 s)	°C
Storage Temperature	Tstg		– 55 to 125	°C
Operating Temperature	Topr	$\langle \langle \rangle$	- 30 to 70	°C

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Parameter	Symbol	Pins	((e	ionditions	Min	Max	Unit
		(7/5)		NORMAL1, 2 mode	4.5		
Supply Voltage			fc = 8 MHz	IDLE1, 2 modes	4.5		
	VDD		fs≂	SLOW mode	27	5.5	V
			32.768 kHz	SLEEP mode	2.7	-	
			\geq	STOP mode	2.0		
Output Voltage	V _{OUT3}	Source open drain ports			V _{DD} – 38	V _{DD}	V
	V _{IH1}	Except hysteresis input	\triangleright		V _{DD} × 0.70		
Input High Voltage	V _{IH2}	Hysteresis input	V V	V _{DD} ≧4.5 V		V _{DD}	V V
	V _{IH3}		v	′ _{DD} <4.5 V			
	V_{IL1}	Except hysteresis input				V _{DD} x 0.30	
Input Low Voltage	V _{IL2}	Hysteresis input		′ _{DD} ≧4.5 V	0	V _{DD} × 0.25	v
	V _{IL3}		V _{DD} <4.5 V			V _{DD} x 0.10	
	fc	XIN, XOUT	VDD	e = 4.5 to 5.5V	0.4	8.0	MHz
Clock Frequency	fs	XTIN, XTOUT			30.0	34.0	kHz

Recommended Operating Conditions. $(V_{SS} = 0V, Topr = -30 to 70^{\circ}C)$

Note 1: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

Note 2: Clock frequency fc: Supply voltage range is specified in NORMAL1/2 mode and IDLE1/2 mode.

DC Chara	cteristics	(V _{SS} = 0 V, To	pr = - 30 to 70°C)				
Parameter	Symbol	Pins	Conditions	Min	Тур.	Max	Unit
Hysteresis Voltage	V _{HS}	Hysteresis input		(0.9	-	V
	I _{IN1}	TEST		\bigcirc))^		
Input Current	I _{IN2}	Open drain ports, Tri-state ports	$V_{DD} = 5.5 V$ $V_{IN} = 5.5 V/0 V$	35	-	± 2	μA
	I _{IN3}	RESET, STOP		2			
Input Posiston co	R _{IN1}	Port P4 with pull-down		30	70	150	
Input Resistance	R _{IN2}	RESET		100	220	450	kΩ
Pull-down Resistance	R _K	Source open drain ports	$V_{DD} = 5.5 V, V_{KK} = -30 V$	-	80	/	
	I _{LO1}	Sink open drain ports	V _{DD} = 5.5 V, V _{OUT} = 5.5 V	- /	<u>21</u>	2	
Output Leakage Current	I _{LO2}	Source open drain ports	$V_{DD} = 5.5 V, V_{OUT} = -32 V$	-	5-	_ -2	μA
	I _{LO3}	Tri-state ports	$V_{DD} = 5.5 V, V_{OUT} = 5.5 V/0 V$	$\frac{1}{2}$)-[±2	
Output Link Voltono	V _{OH2}	Tri-state ports	$V_{DD} = 4.5 V$, $I_{OH} = -0.7 mA$	4.1	40	/ -	v
Output High Voltage	V _{OH3}	P8, P9	$V_{DD} = 4.5 V_{10H} = -5 mA$	2.4	$\sum_{i=1}^{n}$	-	V
Output Low Voltage	V _{OL}	Except XOUT	$V_{DD} = 4.5 V, I_{OL} = 1.6 mA$	$\langle \gamma \rangle$	-	0.4	V
Output High current	I _{OH}		$V_{DD} = 4.5 V, V_{OH} = 2.4 V$	\sum	- 15	-	mA
Supply Current in NORMAL 1, 2 modes			V _{DD} = 5.5 V fc = 8 MHz	-	12	20	mA
Supply Current in IDLE 1, 2 modes			fs = 32.768 kHz V _{IN} = 5.3 V/0.2 V	-	6	10	
Supply Current in SLOW mode	I _{DD}		$V_{DD} = 3.0 V$ fs = 32.768 kHz	-	30	60	
Supply Current in SLEEP mode		C	$V_{IN} = 2.8 V/0.2 V$	_	15	30	Aµ
Supply Current in STOP mode			V _{DD} =5.5 V V _{IN} = 5.3 V/0.2 V	_	0.5	10	μA

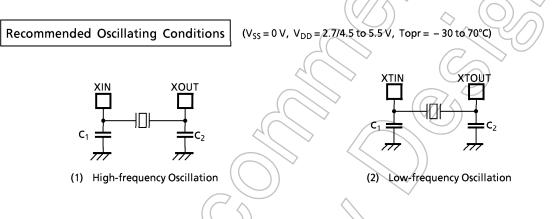
Note 1: Typical values show those at Topr = 25° C, V_{DD} = 5 V.

Note 2: Input Current I_{IN1}, I_{IN3}; The current through resistor is not included, when the input resistor (pull-upor pull-down) is contained.

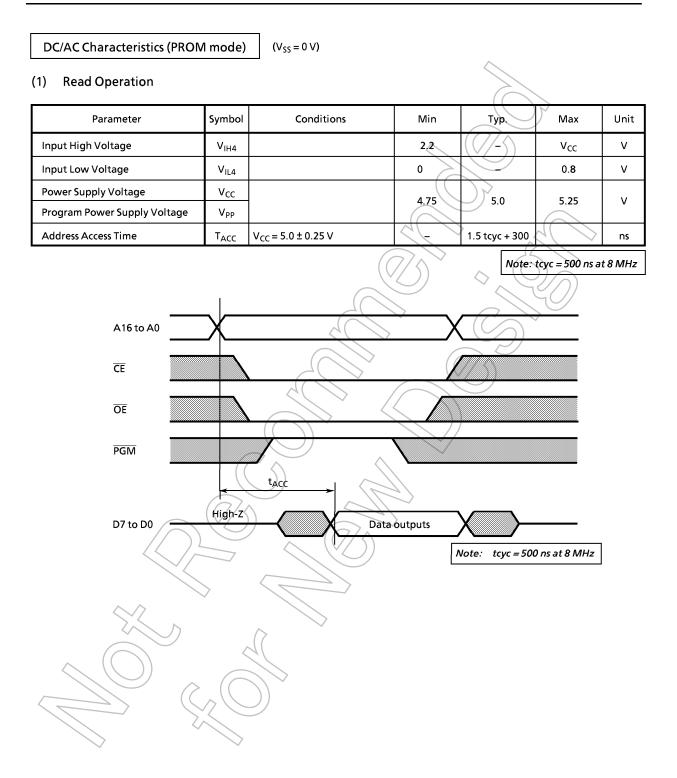
Note 3: Typical current consumption during AD conversion is 1.2 mA.

AD Conversion Charact	teristics $(V_{SS} = 0 V,$	V_{DD} = 4.5 to 5.5 V, Topr = -	30 to 70°C)			
Parameter	Symbol Pins	Conditions	Min	Тур.	Max	Unit
Analog Input Voltage Range	V _{CIN} CIN5 to CIN0		V _{SS}	-	V _{DD}	V
Conversion Error		V _{DD} = 5.0 V	-	-	± 1.5	LSB
	\sim //					

AC Characteristic	s	$(V_{SS} = 0 V, V_{DD} = 2.7/4.5 \text{ to } 5.5 V, \text{ Topr} = -30 \text{ to } 70^{\circ}\text{C})$				
Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
		In NORMAL1, 2 modes	0.5		10	
Machine Cycle Time		In IDLE1, 2 modes	IDLE1, 2 modes 0.5		10	
	Ⅰ ⊦	In SLOW mode	147.0	77	133.3	μs
		In SLEEP mode	117.6	\bigcirc t		
High Level Clock Pulse Width	t _{WCH}	For external clock operation	50			
Low Level Clock Pulse Width	t _{WCL}	(XIN input), fc = 8 MHz		> -	_	ns
High Level Clock Pulse Width	t _{WSH}	For external clock operation				
Low Level Clock Pulse Width	t _{WSL}	(XTIN input), fs = 32.768 kHz	14.7		\bigcirc	μS

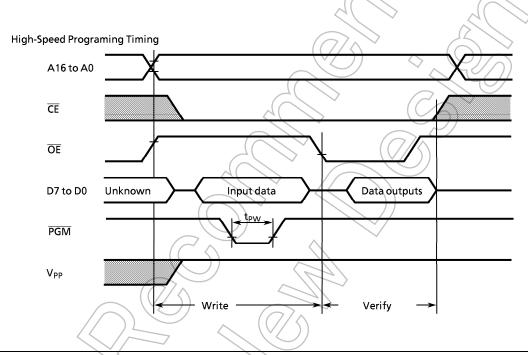


- Note 1: An electrical shield by metal shield plate on the surface of the IC package should be recommendable in order to prevent the device from the high electric fieldstress applied for continuous reliable operation.
- Note 2: The product numbers and specifications of the resonators by Murata Manufacturing Co., Ltd. are subject to change. For up-to-date information, please refer to the following URL; http://www.murata.co.jp/search/index.html



(2) Program Operation (High-Speed program mode) (Topr = $25 \pm 5^{\circ}$ C)

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
Input High Voltage	V _{IH4}		2.2		V _{cc}	v
Input Low Voltage	V _{IL4}		0		0.8	v
Power Supply Voltage	V _{CC}		6.00	6.25	6.5	v
Program Power Supply Voltage	V _{PP}		12.5	12.75	13.0	v
Initial Program Pulse Width	t _{PW}	V _{CC} = 6.25 V V _{PP} = 12.75 ± 0.25	0.095	9.1	0.105	ms



Note 1: When V_{cc} power supply is turned on or after, V_{pp} must be increased.

When V_{cc} power supply is turned off or before, V_{pp} must be decreased.

Note 2: The device must not be set to the EPROM programmer or picked up from it under applying the program voltage (12.5 V \pm 0.5 V = V) to the V_{pp} pin as the device is damaged.

Note 3:Do not apply the parameter of program voltage (more than + 13 V) including overshoot to the V_{pp} pin.

Note 4:Be sure to execute the recommended programing mode with the recommended programing adaptor. If a mode or an adaptor except the above, the misoperation sometimes occurs.

